Solder profile for lead free reflow process

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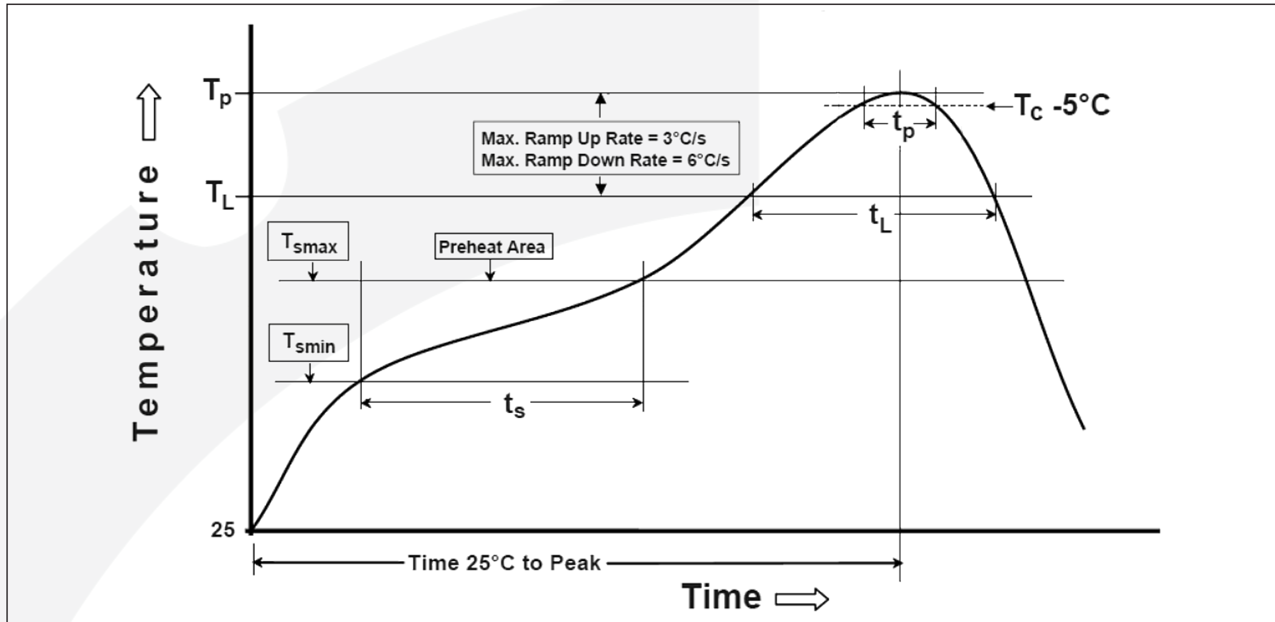

Profile Feature	Pb-Free Assembly
Preheat/Soak	
Temperatur Min (T_{smin})	150°C
Temperature Max (T_{smax})	200°C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds
Ramp-Up Rate (T_L to T_p)	3°C/second max.
Liquidous temperature (T_L)	217°C
Time (t_L) maintained above T_L	60-150 seconds
Peak package body temperature (T_p)	For users T_p must not exceed the Classification temp in Table 2 For suppliers T_p must equal or exceed the Classification temp in Table 2
Time (t_p) within 5°C of the specified classification temperature (T_C)	30 seconds
Ramp-down rate (T_p to T_L)	6°C/sec max.
Time 25°C to peak temperature	8 minutes max.

Table 1: Classification Reflow Profiles (refer to IPC/JEDEC J-STD-020D)

Package Thickness	Volume < 350 mm³	Volume 350 - 2000 mm³	Volume > 2000 mm³
< 1.6 mm	260°C	260°C	260°C
1.6 mm - 2.5 mm	260°C	250°C	245°C
≥ 2.5 mm	250°C	245°C	245°C

Note: All temperatures refer to topside of the package, measured on the package body surface

Table 2: Package Classification Reflow Temperature (refer to IPC/JEDEC J-STD-020D)

All information given without liability. Our component layout is designed to the above shown profile. Nevertheless, an individual validation of the soldering behaviour in the customer´s application is necessary. If you require further information, do not hesitate to contact our representatives.

Kaschke Components GmbH

Rudolf-Winkel-Straße 6 · 37079 Göttingen · Germany
Fon +49 (0) 551-5058-6 · Fax +49 (0) 551-65756
kaschke.de

RoHS compatible